Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.015”**

**B**

**E**

**.013”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size = .0027 x .0027”**

**Backside Potential: COLLECTOR**

**Mask Ref: 43**

**APPROVED BY: DK DIE SIZE .013” X .015” DATE: 9/7/21**

**MFG: FAIRCHILD THICKNESS .008” P/N: 2N918**

**DG 10.1.2**

#### Rev B, 7/1